

**AMENDMENTS TO THE CLAIMS, COMPLETE LISTING OF CLAIMS
IN ASCENDING ORDER WITH STATUS INDICATOR**

Please amend the following claims as indicated.

1. (Currently Amended) A process for a molded article which is shaped by molding, comprising:

shaping a material comprising a thermosetting resin composition containing 100 parts by weight of a thermosetting resin and 0.1 to 100 parts by weight of an inorganic compound dispersed in said thermosetting resin in a die by transferring a shape of the die the inorganic compound being at least one of silica and laminar silicate, and characterized in that the dispersion particle diameter of the silica being said inorganic compound is 2 μm or less and the laminar silicate having an average length of 0.01 to 3 μm and;

curing the material after shaping to obtain the molded article wherein not less than 75% of the shape of the article molded before curing is maintained after the resin composition is cured.

2. (Currently Amended) The thermosetting resin composition process for a molded article according to claim 1, wherein said inorganic compound is an inorganic compound containing silicon and oxygen as constituent elements.

3. (Currently Amended) The thermosetting resin composition process for a molded article according to claim 1 or 2, wherein said inorganic compound is laminar silicate.

4. (Currently Amended) The thermosetting resin composition process for a molded article according to claim 1 or 2, wherein said resin composition contains an epoxy resin as said thermosetting resin.

5. (Currently Amended) A material for substrates, characterized in that said material is composed by using the thermosetting resin composition substrate comprising the molded article obtained by the process for the molded article according to claim 1 or-2 4.

6. (Currently Amended) A film for substrates, characterized in that said film is composed by using the thermosetting resin composition comprising the molded article obtained by the process for the molded article according to claim 1 or-2 4.

7. (Currently Amended) The thermosetting resin composition process for a molded article according to claim 3, wherein said resin composition contains an epoxy resin as said thermosetting resin.

8. (Currently Amended) A material for substrates, characterized in that said material is composed by using the thermosetting resin composition substrate comprising the molded article obtained by the process for the molded article according to claim 3.

9. (Currently Amended) A material for substrates, characterized in that said material is composed by using the thermosetting resin composition substrate comprising the molded article obtained by the process for the molded article according to claim 4.

10. (Currently Amended) A film for substrates, characterized in that said film is composed by using the thermosetting resin composition substrate comprising the molded article obtained by the process for the molded article according to claim 3.

11. (Currently Amended) A film for substrates, characterized in that said film is composed by using the thermosetting resin composition substrate comprising the molded article obtained by the process for the molded article according to claim 4.